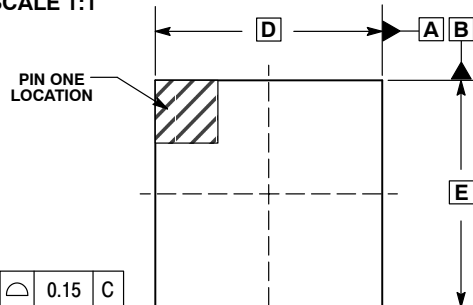
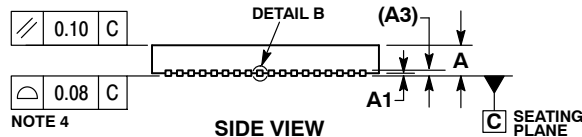




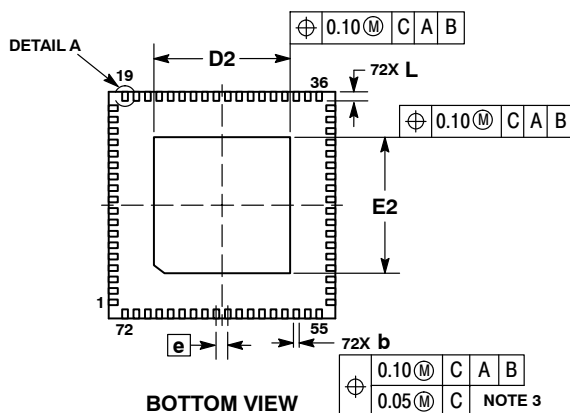
SCALE 1:1



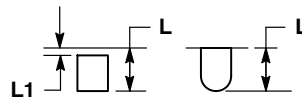
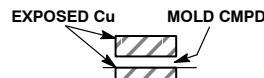
TOP VIEW



SIDE VIEW



BOTTOM VIEW

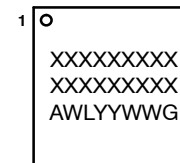
QFN72 10x10, 0.5P
CASE 485DK
ISSUE O

DETAIL A
ALTERNATE
CONSTRUCTIONS

DETAIL B
ALTERNATE
CONSTRUCTION

DATE 12 NOV 2013

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.25mm FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

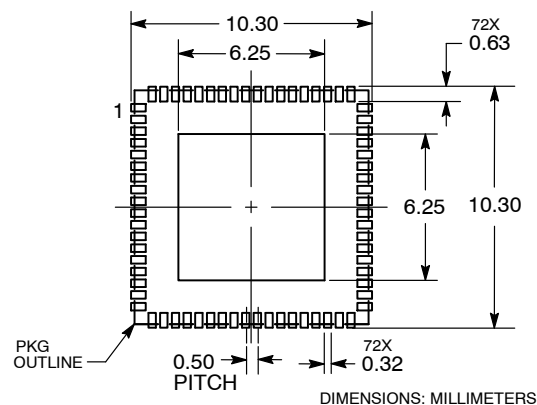
MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A3	0.20	REF
b	0.18	0.30
D	10.00	BSC
D2	5.85	6.15
E	10.00	BSC
E2	5.85	6.15
e	0.50	BSC
L	0.30	0.50
L1	0.00	0.15

GENERIC
MARKING DIAGRAM*


XXXXXX = Specific Device Code
A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED
SOLDERING FOOTPRINT


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DESCRIPTION:	QFN72 10x10, 0.5P	PAGE 1 OF 1

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